DGG PACKAGE



- Suited for SVGA, XGA, or SXGA Display **Data Transmission From Controller to Display With Very Low EMI**
- **Three Data Channels and Clock** Low-Voltage Differential Channels In and 21 Data and Clock Low-Voltage TTL **Channels Out**
- **Operates From a Single 3.3-V Supply**
- **Tolerates 4-kV HBM ESD**
- Packaged in Thin Shrink Small-Outline Package (TSSOP) With 20-Mil Terminal Pitch
- Consumes Less Than 1 mW When Disabled
- Wide Phase-Lock Input Frequency Range of 31 MHz to 68 MHz
- No External Components Required for PLL
- Inputs Meet or Exceed the Standard Requirements of ANSI EIA/TIA-644 **Standard**
- Improved Replacement for the DS90C364 and SN75LVDS86
- **Improved Jitter Tolerance**
- See SN65LVDS86A-Q1 Data Sheet for Information About the Automotive **Qualified Version**

(TOP VIEW) D17 48 🛮 V_{CC} D18 **∏** 47 D16 2 GND [] 3 46 D15 D19 🛮 4 45 D14 D20 **1** 5 44 ∏ GND NC ∏ 6 43 D13 LVDSGND 42 VCC AOM Π 41 **Π** D12 40 D11 A0P **∏** 9 A1M **1** 10 39**∏** D10 A1P **∏** 38 | GND 11 LVDSV_{CC} 12 37 D9 36 V_{CC} LVDSGND 1 13 A2M **∏** 35 D8 14 A2P □ 34 D7 15 CLKINM **∏** 16 33 **∏** D6 CLKINP [17 32 **∏** GND LVDSGND 1 18 31 **D** D5 PLLGND **□** 19 30 **∏** D4 PLLV_{CC} [] 20 29 **∏** D3 PLLGND 1 21 28 🛛 V_{CC} SHTDN I 22 27 D2 CLKOUT [23 26 D1 24 25 T GND ро П

NC - Not connected

description

The SN65LVDS86A/SN75LVDS86A FlatLink™ receiver contains three serial-in 7-bit parallel-out shift registers and four low-voltage differential signaling (LVDS) line receivers in a single integrated circuit. These functions allow receipt of synchronous data from a compatible transmitter, such as the SN75LVDS81, '83, '84, or '85, over four balanced-pair conductors and expansion to 21 bits of single-ended low-voltage LVTTL synchronous data at a lower transfer rate.

When receiving, the high-speed LVDS data is received and loaded into registers at seven times the LVDS input clock (CLKIN) rate. The data is then unloaded to a 21-bit-wide LVTTL parallel bus at the CLKIN rate. The LVDS86A presents valid data on the falling edge of the output clock (CLKOUT).

The 'LVDS86A requires only four line-termination resistors for the differential inputs and little or no control. The data bus appears the same at the input to the transmitter and output of the receiver with the data transmission transparent to the user(s). The only user intervention is the possible use of the shutdown/clear (SHTDN) active-low input to inhibit the clock and shut off the LVDS receivers for lower power consumption. A low level on this signal clears all internal registers to a low level.

The SN75LVDS86A is characterized for operation over ambient free-air temperatures of 0°C to 70°C. The SN65LVDS86A is characterized for operation over the full Automotive temperature range of -40°C to 125°C.

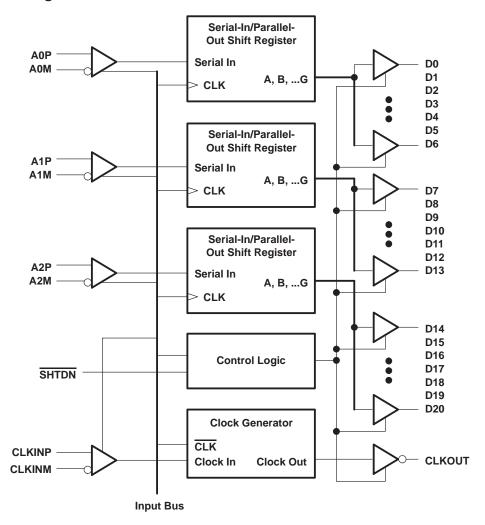


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functional block diagram



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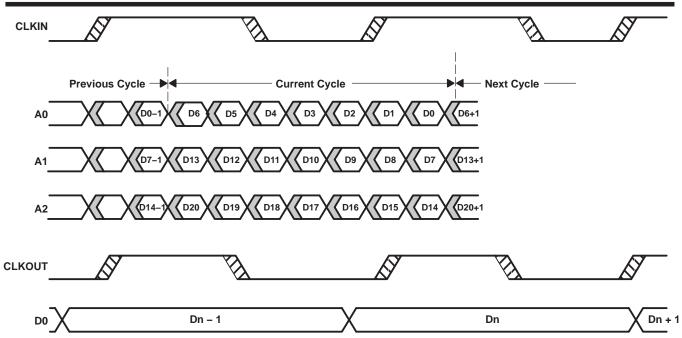
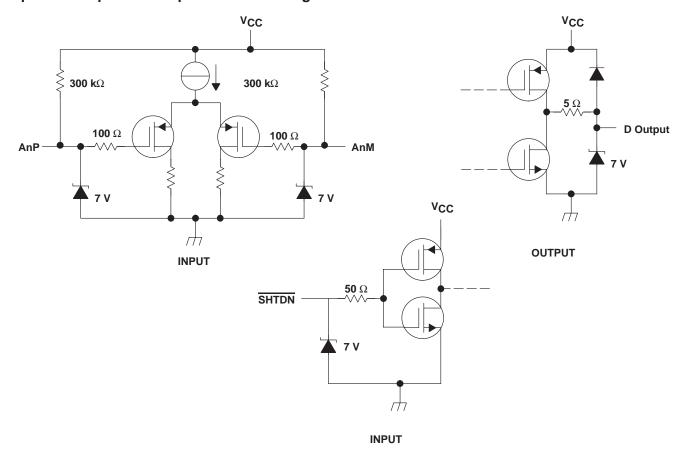


Figure 1. SN65LVDS86A/SN75LVDS86A Load and Shift Timing Sequences

equivalent input and output schematic diagrams





SLLS318D - NOVEMBER 1998 - REVISED NOVEMBER 2007

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

NOTES: 1. All voltage values are with respect to the GND terminals unless otherwise noted.

2. This rating is measured using MIL-STD-883C Method, 3015.7.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR [‡] ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 125°C POWER RATING
DGG	1637 mW	13.1 mW/°C	1048 mW	327 mW

[‡] This is the inverse of the junction-to-ambient thermal resistance when board mounted and with no air flow.

recommended operating conditions (see Figure 2)

	·	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		3	3.3	3.6	V
High-level input voltage, V _{IH} (SHTDN)		2			V
Low-level input voltage, V _{IL} (SHTDN)				0.8	V
Magnitude differential input voltage, V _{ID}		0.1		0.6	V
Common-mode input voltage, V _{IC}		$\frac{ V_{\text{ID}} }{2}$	2	$2.4 - \frac{ V_{ID} }{2}$	V
	SN75LVDS86A			70	
Operating free-air temperature, T _A	SN65LVDS86A	-40		125	°C

timing requirements

	MIN	NOM	MAX	UNIT
Cycle time, input clock, $t_{\mathbb{C}}$ §	14.7	t _C	32.4	ns

[§] Parameter to is defined as the mean duration of a minimum of 32 000 clock cycles.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST C	ONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IT+}	Positive-going differential input threshold voltage					100	mV
VIT-	Negative-going differential input threshold voltage [‡]			-100			mV
Vон	High-level output voltage	$I_{OH} = -4 \text{ mA}$		2.4			V
VOL	Low-level output voltage	I _{OL} = 4 mA				0.4	V
		Disabled,	All inputs to GND			280	μΑ
		Enabled, AnM = 1.4 V,	,		33	40	
Icc	Quiescent current (average)	Enabled, Grayscale patt t _C = 15.38 ns		43		mA	
		Enabled, Worst-case pa t _C = 15.38 ns	C _L = 8 pF, ttern (see Figure 4)		68		
lіН	High-level input current (SHTDN)	VIH = VCC				±20	μΑ
	Lauring Cutton	., .	SN75LVDS86A			±20	•
I L	Low-level input current (SHTDN)	V _{IL} = 0	SN65LVDS86A			±25	μΑ
lį	Input current A inputs	$0 \le V_I \le 2.4 \text{ V}$				±20	μΑ
loz	High-impedance output current	VO = 0 or VCC	<u> </u>			±10	μΑ

 $^{^{\}dagger}$ All typical values are at VCC = 3.3 V, TA = 25°C.

switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
t _{su}	Setup time, D0–D20 to CLKOUT↓	0 0 5 0 5 5 0 5	5			ns
th	Data hold time, CLKOUT↓ to D0–D20	C _L = 8 pF, See Figure 5	5			ns
t(RSKM)	Receiver input skew margin§ (see Figure 7)	$t_{\rm C}$ = 15.38 ns (±0.2%), Input clock jitter < 50 ps¶,	550	700		ps
t _d	Delay time, CLKIN↑ to CLKOUT↓ (see Figure 7)	$V_{CC} = 3.3 \text{ V},$ $t_{C} = 15.38 \text{ ns } (\pm 0.2\%), T_{A} = 25^{\circ}\text{C}$	3	5	7	ns
t _{en}	Enable time, SHTDN to phase lock	See Figure 7		1		ms
t _{dis}	Disable time, SHTDN to off state	See Figure 8		400		ns
t _t	Transition time, output (10% to 90% $t_{\rm f}$ or $t_{\rm f}$) (data only)	C _L = 8 pF		3		ns
t _t	Transition time, output (10% to 90% $t_{\rm f}$ or $t_{\rm f}$) (clock only)	C _L = 8 pF		1.5		ns
t _W	Pulse duration, output clock			0.50 t _C		ns

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] The algebraic convention, in which the less-positive (more-negative) limit is designated minimum, is used in this data sheet for the negative-going input voltage threshold only.

[§] The parameter $t_{(RSKM)}$ is the timing margin available to allocate to the transmitter and interconnection skews and clock jitter. The value of this parameter at clock periods other than 15.38 ns can be calculated from $t_{RSKM} = t_c/14 - 550$ ps.

 $[\]P$ |Input clock jitter| is the magnitude of the change in input clock period.

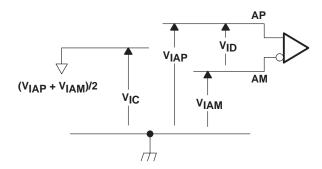
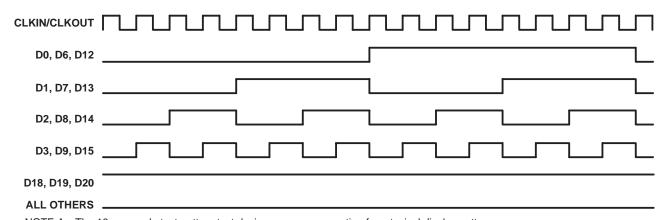
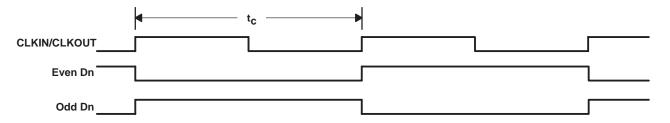


Figure 2. Voltage Definitions



 ${\sf NOTE\ A:}\quad {\sf The\ 16-grayscale\ test-pattern\ test\ device\ power\ consumption\ for\ a\ typical\ display\ pattern.}$

Figure 3. 16-Grayscale Test-Pattern Waveforms



NOTE A: The worst-case test pattern produces nearly the maximum switching frequency for all of the LVTTL outputs.

Figure 4. Worst-Case Test-Pattern Waveforms



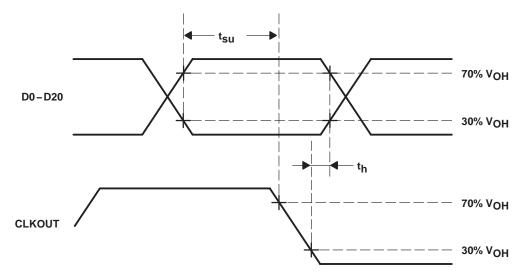
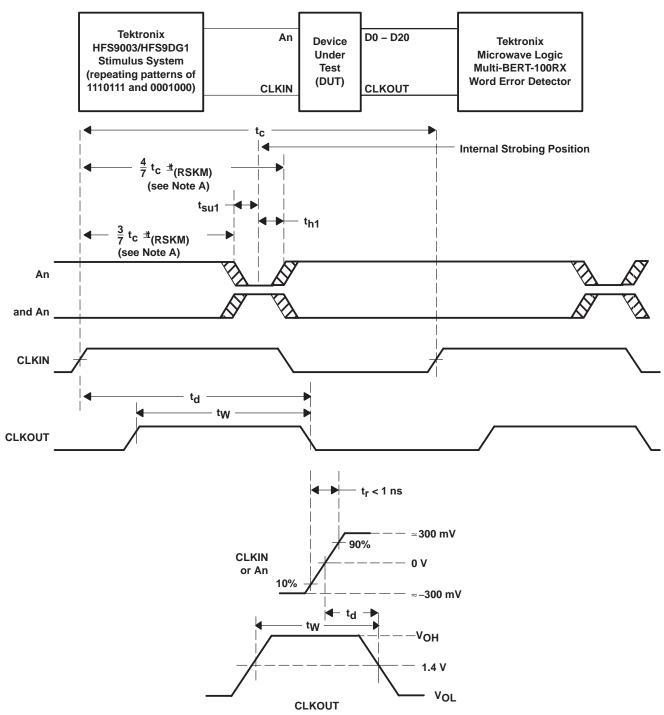


Figure 5. Setup and Hold Time Waveforms



NOTE A: CLKIN is advanced or delayed with respect to data until errors are observed at the receiver outputs. The advance or delay is then reduced until there are no data errors observed. The magnitude of the advance or delay is t_(RSKM).

Figure 6. Receiver Input Skew Margin, Setup/Hold Time, and Delay Time Definitions



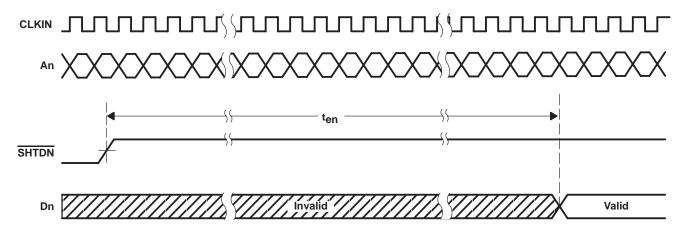


Figure 7. Enable Time Waveforms

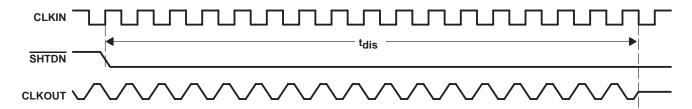


Figure 8. Disable Time Waveforms

TYPICAL CHARACTERISTICS

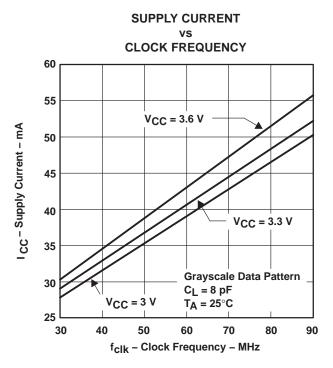
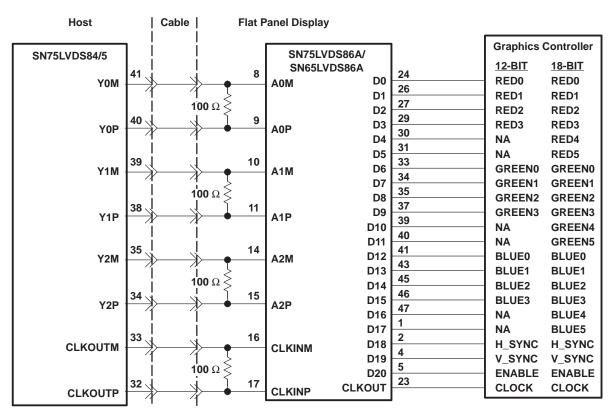


Figure 9. RMS Grayscale I_{CC} vs Clock Frequency



APPLICATION INFORMATION

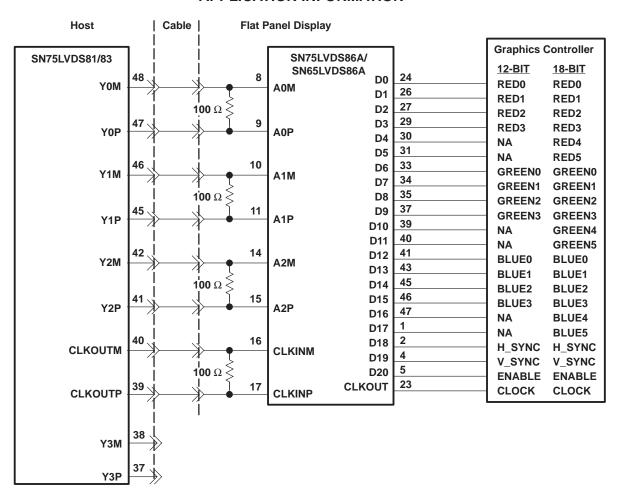


NOTES: A. The four 100- Ω terminating resistors are recommended to be 0603 types.

B. NA - not applicable, these unused inputs should be left open.

Figure 10. 18-Bit Color Host to Flat Panel Display Application

APPLICATION INFORMATION



NOTES: A. The four 100- Ω terminating resistors are recommended to be 0603 types.

B. NA - not applicable, these unused inputs should be left open.

Figure 11. 24-Bit Color Host to 18-Bit Color LCD Panel Display Application

See the *FlatLink*™ *Designer's Guide* (SLLA012) for more application information.





10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN65LVDS86AQDGG	ACTIVE	TSSOP	DGG	48	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	65LVDS86AQ	Samples
SN65LVDS86AQDGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	65LVDS86AQ	Samples
SN75LVDS86ADGG	ACTIVE	TSSOP	DGG	48	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	0 to 70	SN75LVDS86A	Samples
SN75LVDS86ADGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR		SN75LVDS86A	Samples
SN75LVDS86ADGGRG4	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR		SN75LVDS86A	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

10-Dec-2020

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OTHER QUALIFIED VERSIONS OF SN65LVDS86A:

Automotive: SN65LVDS86A-Q1

NOTE: Qualified Version Definitions:

Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

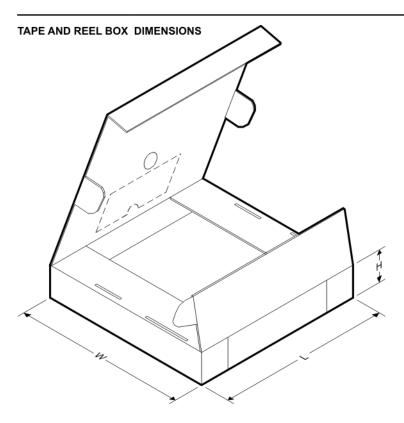
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LVDS86AQDGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN75LVDS86ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1

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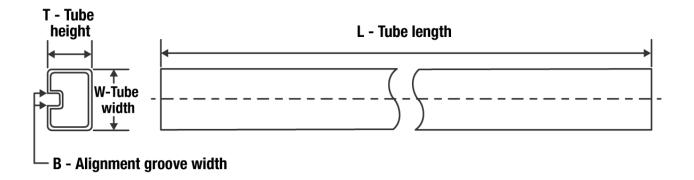
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LVDS86AQDGGR	TSSOP	DGG	48	2000	350.0	350.0	43.0
SN75LVDS86ADGGR	TSSOP	DGG	48	2000	350.0	350.0	43.0

PACKAGE MATERIALS INFORMATION

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TUBE

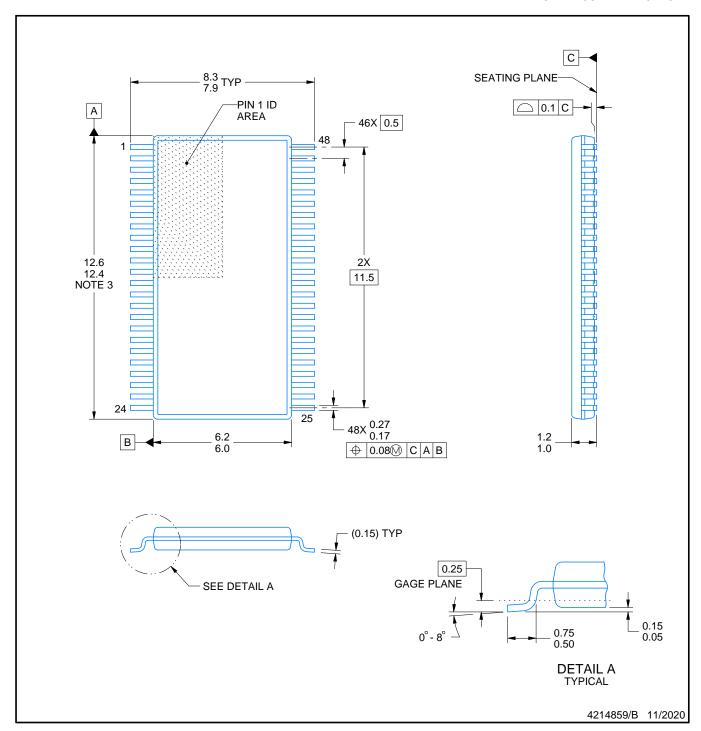


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN65LVDS86AQDGG	DGG	TSSOP	48	40	530	11.89	3600	4.9
SN75LVDS86ADGG	DGG	TSSOP	48	40	530	11.89	3600	4.9



SMALL OUTLINE PACKAGE



NOTES:

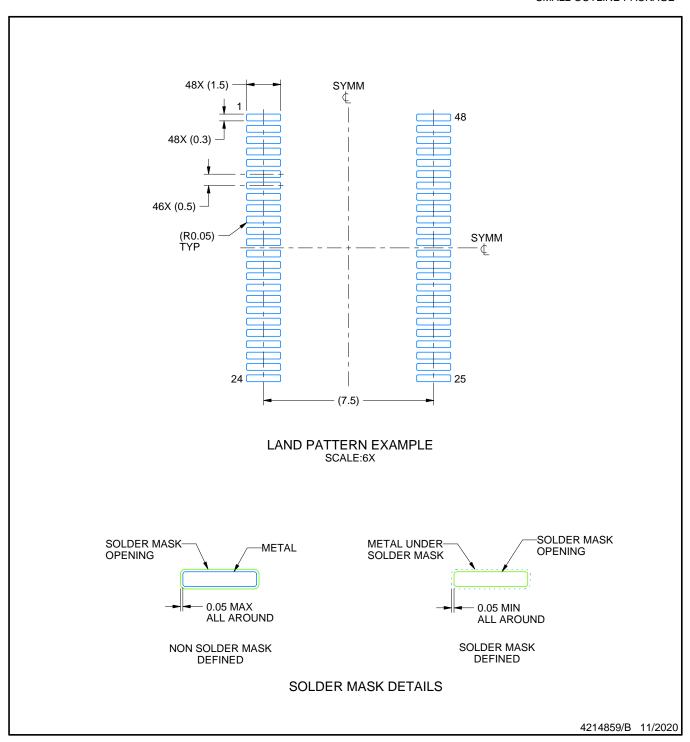
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

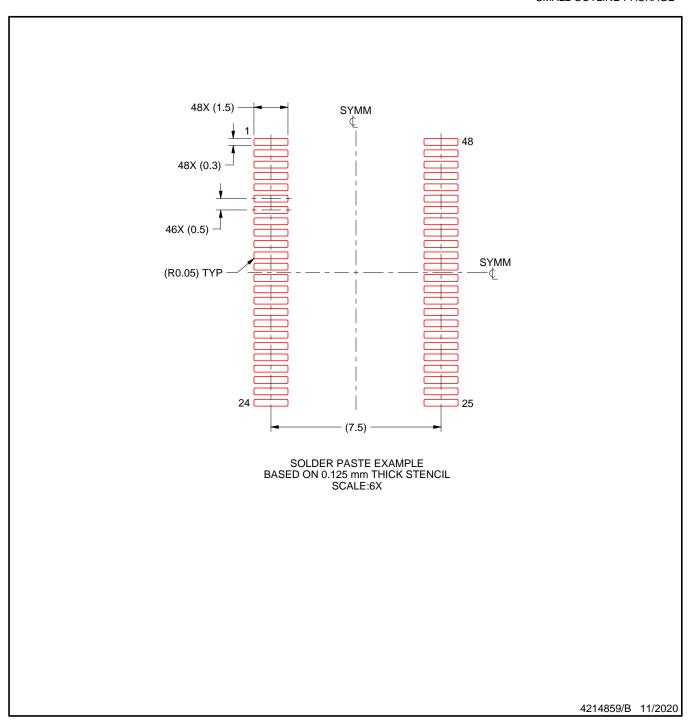


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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